

**SP-TMEP70ASP****Thermoplastic Modified Epoxy Resin**

SP-TMEP70ASP: The benefits of thermoplastic modified epoxy resins have been described in academic literature. However, commercial availability has been limited. Now a series of thermoplastic modified epoxy resins are available commercially using proprietary engineered thermoplastics to produce epoxy resins possessing many of the advantages of rubber modified epoxies without their associated deficiencies. Compared to rubber modified materials, thermoplastic modified epoxies maintain higher glass transition temperatures with reduced sensitivity to moisture and humidity. These resins can be used as a thermoplastic or may be cured using conventional curing technologies for single component systems e.g., with DICY (dicyandiamide).

Issue Date:	9/14/2023
Specific Physical Form:	Solid Flake or Granulated
Color:	Amber to Brown
General Physical Form:	Solid
Shelf Life:	3 Years

Typical Properties -

Specific Gravity:	1.2
Epoxy Equivalent Weight:	560 - 660 g/eq.
Ring and Ball Softening Point:	110°C
Viscosity at 120°C:	10,000 - 40,000 Poise
Hydroxyl Equivalent Weight:	390 - 400 g/eq.

Estimated Molecular Weight of
Polymeric Portion:

Mn = 6,000 - 12,000 g/mol
Mw = 25,000 - 35,000 g/mol

Disclaimer:

The information provided herein was believed to be accurate at the time of preparation and is supplied to assist in using this product. No liability will be accepted in application of the information in this data sheet and no guarantee of performance results is given in any particular user application. It is the responsibility of the user to fully investigate and determine the suitability of this product for any intended use.

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